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FDS6681Z

30 Volt P-Channel PowerTrench[®] MOSFET General Description

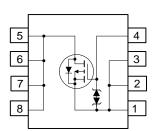
This P-Channel MOSFET is produced using ON Semiconductor's advanced PowerTrench[®] process that has been especially tailored to minimize the on-state resistance.

This device is well suited for Power Management and load switching applications common in Notebook Computers and Portable Battery Packs.

Features

- -20 A, -30 V. $R_{DS(ON)} = 4.6 \text{ m}\Omega @ V_{GS} = -10 \text{ V}$ $R_{DS(ON)} = 6.5 \text{ m}\Omega @ V_{GS} = -4.5 \text{ V}$
- + Extended V_{GSS} range (–25V) for battery applications
- HBM ESD protection level of 8kV typical (note 3)
- High performance trench technology for extremely low R_{DS(ON)}
- High power and current handling capability
- Termination is Lead-free and RoHS Compliant





Absolute Maximum Ratings $T_A=25^{\circ}C$ unless otherwise noted

Symbol		Parameter		Ratings	Units
V _{DSS}		ource Voltage		-30	V
V _{GSS}	Gate-So	urce Voltage		±25	V
I _D	Drain Cu	urrent – Continuous	(Note 1a)	-20	A
		- Pulsed		-105	
> _D	Power D	issipation for Single Operation	(Note 1a)	2.5	W
			(Note 1b)	1.2	
			(Note 1c)	1.0	
T _J , T _{stg}	Operatin	g and Storage Junction Temper	ature Range	-55 to +150	°C
Therma	al Chara	acteristics			
		acteristics Resistance, Junction-to-Ambier	nt (Note 1a)	50	°C/W
Therma R _{0JA} R _{0JC}	Thermal		Note 1a) (Note 1)	50 25	°C/W
ર _{θJA} ર _{θJC}	Thermal Thermal ge Mark	Resistance, Junction-to-Ambier Resistance, Junction-to-Case ing and Ordering Int	(Note 1)		

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Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics				1	
BV _{DSS}	Drain–Source Breakdown Voltage	$V_{GS} = 0 V$, $I_D = -250 \mu A$	-30			V
ΔBV _{DSS} ΔTJ	Breakdown Voltage Temperature Coefficient	$I_D = -250 \ \mu$ A, Referenced to 25°C		-26		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -24 V, V_{GS} = 0 V$			-1	μA
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 25 \text{ V}, V_{DS} = 0 \text{ V}$			±10	μA
On Chara	Acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	-1	-1.8	-3	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate Threshold Voltage Temperature Coefficient	$I_D = -250 \ \mu$ A, Referenced to 25° C		6		mV/°C
$R_{\text{DS(on)}}$	Static Drain–Source On–Resistance	$ \begin{array}{l} V_{GS} = -10 \ V, \ \ I_D = -20 \ A \\ V_{GS} = -4.5 \ V, \ \ I_D = -17 \ A \\ V_{GS} = -10 \ V, \ \ I_D = -20 \ A, \\ T_J = 125^{\circ} C \end{array} $		3.8 5.2 5.0	4.6 6.5 6.3	mΩ
g _{FS}	Forward Transconductance	$V_{DS} = -5 V$, $I_D = -20 A$		79		S
Dvnamic	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = -15 V$, $V_{GS} = 0 V$,		7540		pF
C _{oss}	Output Capacitance	f = 1.0 MHz		1400		pF
C _{rss}	Reverse Transfer Capacitance	7		1120		pF
Switchin	G Characteristics (Note 2)					
t _{d(on)}	Turn–On Delay Time			20	35	ns
tr	Turn–On Rise Time			9	18	ns
t _{d(off)}	Turn–Off Delay Time	7		660	1060	ns
t _f	Turn–Off Fall Time	7		380	610	ns
Q _{g(TOT)}	Total Gate Charge at $V_{GS} = -10V$	$V_{DS} = -15 \text{ V}, I_{D} = -20 \text{ A}$		185	260	nC
Q _{g(TOT)}	Total Gate Charge at $V_{GS} = -5V$			105	150	nC
Q_{gs}	Gate-Source Charge			26		nC
Q _{gd}	Gate-Drain Charge			47		nC

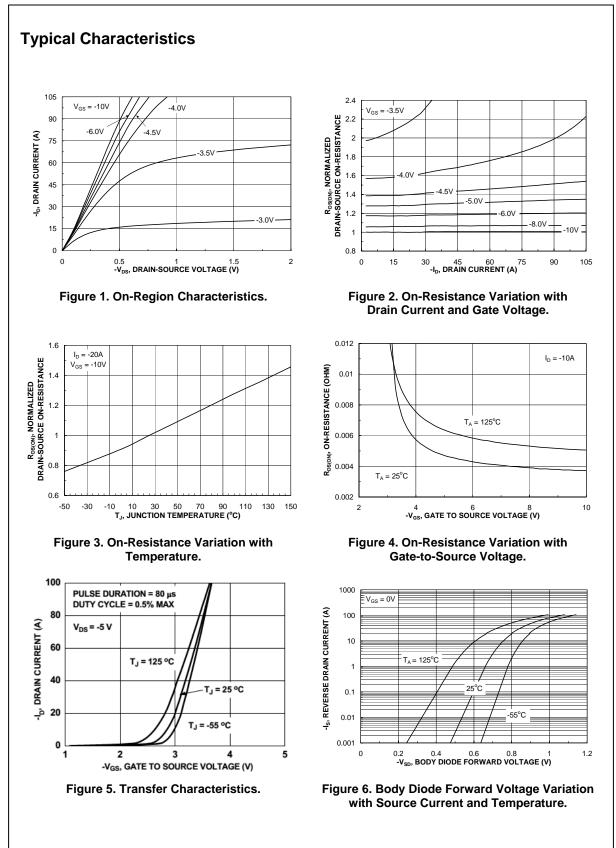
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Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Drain-So	ource Diode Characteristics a	nd Maximum Ratings				
Is	Maximum Continuous Drain-Source	Diode Forward Current			-2.1	А
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 V$, $I_S = -2.1 A$ (Note 2)		-0.7	-1.2	V
t _{RR}	Reverse Recovery Time	$I_{F} = -20 A,$		125		ns
Q _{RR}	Reverse Recovery Charge	dI _F /dt = 100 A/µs (Note 2)		94		nC
. R _{eja} is the su	im of the junction-to-case and case-to-ambient them	mai resistance where the case thermal reference is	defined as	the solder n	nounting su	inface of the
drain pins. R ແມ	$R_{\theta,\text{DC}}$ is guaranteed by design while $R_{\theta,\text{CA}}$ is determine	ed by the user's board design.			-	

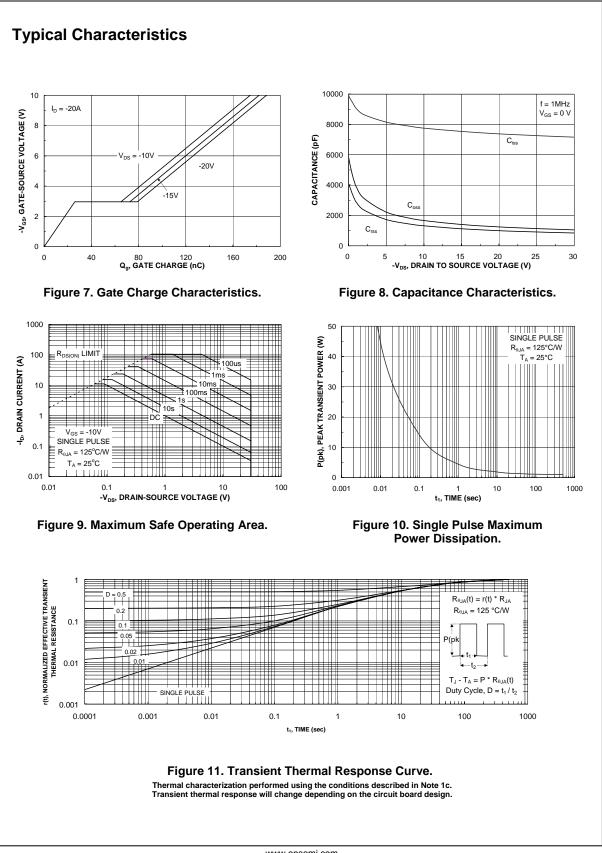
Scale 1 : 1 on letter size paper

2. Pulse Test: Pulse Width < 300 $\mu s,$ Duty Cycle < 2.0%

3. The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.



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